Procedural Review Voting Sheet 2014 Cycle 7

REGION: Japan

COMMITTEE: Traceability Committee
1 EVENT: SEMICON Japan 2014
2 DATE OF MEETING: 2014/12/05

3 PLACE OF MEETING: Tokyo Big Sight, Tokyo

COMMITTEE CO-CHAIRS: Yoichi Iga/JSA, Hirokazu Tsunobuchi/Keyence

SEMI STAFF: Chie Yanagisawa

A&R Voter: Name/Company

Date: 200X/MM/DD

I. Document Number & Title

Document	Document Title: Revision to SEMI T7-0303
5752	(Reapproved 0709) "Specification for Back Surface
	Marking of Double-Side Polished Wafers with a
	Two-Dimensional Matrix Code Symbol"

II. Tally (Staff to fill in)

Voting Tally: As-cast tally after close of voting period

A minimum of 60% of the voting interests that have voting members within the technical committee must return votes. (Regulations \P 9.6.1)

	Return		Distribution		Return Rate	
Yellow	29	÷	48	=	60.4%	>=60%
Lilac & Others	22					
Total Vote	51					
Reject	1					
Accept	21					

A&R	Not approved
Adit	Reason:

III. Rejects

Reject 1 (John Vally / SunEdison Semiconductor Limited) Negative 1 of Reject 1

	Referenced		.3.1.1 and Table 1					
	Section							
		Both 5.3.1.1 and Table 1 should be changed to use SEMI M20 coordinates. All wafer metrology and subsequent process interferences which might occur due to this T7 mark will use M20 coordinates. For example, wafer dimensional metrology tools report the wafer thickness disruption in M20 coordinates.						
Neg		Existing: 5.3.1.1 The 8 row \times 32 column rectangular 2-D matrix code symbol shall be placed so that the reference point is located the distance as given in Table 1 from the center of the wafer, along a radius $5.0 \pm 0.1^{\circ}$ counterclockwise from the orientation fiducial axis.						
Negative	Reason	5.3 (se spe up Th	oposed 8.1.1 The 2-D matrix code symbole Fig. 3) so that the reference posterified as given in Table 1. Who ward the mark lies at $5.0 \pm 0.1^{\circ}$ de SEMI M20 coordinates specificated and easily relate to specificate	int is located en viewed fr counterclock ed in Table 1	at the radial distance on above with the wise from the original do not change w	ance from wafer cent he back side facing entation fiducial axis when the wafer is	ter	
		Proposed Table 1:						
			Table 1 Code Symbol Reference	ce Point Loca	tion (SEMI M20 d	coordinate space)		
		Ν	Iominal Wafer Diameter (mm)	Radius (mn	n) Theta (deg.)	~ x(mm) ~ y(mm	1)	
			300	148.95 ± 0.1		-12.98 -148.38	_	
		<u>. </u>	450	223.95 ± 0.1	5 265 ± 0.1	-19.52 -223.10)	
			No withdrawal made			GO TO "Related" section	,,	
	Withdrawal	Х	Withdrawal document receives 25, 2014	GO TO "Final" -2	>			
			"Related" is mutually agreed	l upon.				
	Motion and		*This motion can be appersuasive Section)	pended to	the motion f	or Persuasive (S	See	
	Reason		Negative is related (needs	over 1/3 vo	tes to pass)			
		Negative is not related (needs 2/3 or more votes to pass)						
		Reason XXXX						
₹ela	Motion by/2nd by	Na	me (Company)/Name (Comp					
Related	Discussion							
		ХХ	(-XX					
	Result of Vote		[Negative is related] > 1/3		GO TO "Persu	ıasive"		
	(check ONE)		[Negative is not related] < 2/	/3	JO TO FEISU	iu 31 V C		
			2/3=< [Negative is not relate	ed]	GO TO "Final"	' → (B)		

	Motion and			ative is related and persuasive (needs over 1/3				
	Reason		Negative is related and not persuasive (needs 2/3 or more votes to pass)					
			Reas					
	Motion by/2nd by	Na	me (C	Company)/Name (Company)				
٦,	Discussion							
ers		XX	(-XX					
Persuasive			[Negative is related and persuasive] > 1/3			"Final" →		
/e	Result of Vote		[Neg	ative is related and not persuasive] < 2/3	(E)			
	(check ONE)		2/3=	<[Negative is related and not persuasive] <90%	GO TO	"Final" →		
			90%	=< [Negative is related and not persuasive]	GO TO Significa Option"	"Not nt Finding		
Not Significant Finding Option			It is ı	mutually agreed upon to term the negative "not s	ignificant"	GO TO →		
nt Fir			It is i	mutually agreed upon to term the negative "signi	ficant"	GO TO →		
ding	Motion			negative is "not significant".		(C)		
do f	Motion by/2nd by	No		Company)/Name (Company)				
tion	monon by/zna by	INC	, i		TO -2 (D)			
	Vote				TO → (D)			
					TO → (C)			
			gative					
		X	(A)	withdrawn (counted under h in disposition)				
	Final		(B)	not related (counted under i in disposition)				
			(C)	related and not persuasive (significant)				
			(D)	not significant (counted under j in disposition) related and persuasive DOCUMENT FAIL	e			
			(E)	1	.ა			
		Х		ment generated. See IV Comments, #5				
Δ	Not ap	pro	ved					
	Reason:							

Disposition of Reject 1

1	Original numbe	Original number of Negatives (g)						
1	# of Negatives	withd	rawn		(h)			
0	# of Negatives	found	I not related		(i)			
0	# of Negatives	found	I not significant		(j)			
		Х	g -(h + i + j)=0	☐ Reject is Not Valid denominator of § VI. Appro	and is not included in the oval Conditions Check			
	Final g -(h + i + j)>0			☐ Reject is included in the denominator of § VApproval Conditions Check				
			Reject without a Negative	□Not Valid				

Note: If all of the negative material included with a reject vote is withdrawn, determined to be not related, or determined to be not significant, the reject vote is not valid. (Regulations ¶ 9.4.3.3)

AOD		Not approved
A&R	Re	eason:

IV. Comments

0	ı	Referenced Section		Section 2.1 and Figure 1					
om		Fr	om	Dr. Rafael Vargas-Bernal (Instituto Tecnologico Superior de Irapuato)					
Comment	Comment			In subsection 2.1 "diamters" must be changed by "diameters". In Figure 1 "CL" must be separated to be clear its reading.					
		Discu	ussion	Editorial Change in "V. Summary of Editorial Changes"					
		The	e commit	tee agreed to do one of the following actions.					
		*No	motion	is required in this step.					
			No furth	er action was taken by the committee.					
			Refer to	the task force for more consideration.					
\ \			New Bus	siness					
Action			Other	rther					
on proposed	Editorial Change								
			Case 1:	No vote in this section :					
			To be in	cluded and voted on in <u>§ 5. Summary of Editorial Changes</u> .					

	Case	2: Voted in this section :					
		nal section number and at least one full sentence are required in "FROM" and fields.					
	FRO	M: Section xxx					
1	To: S	Section xxx					
	Just	fication (If necessary)					
	FRO	FROM: Section xxx					
2	To: S	Section xxx					
	Just	ification (If necessary)					
Motion	otion by/2nd Name (Company)/Name (Company)						
V	ote	XX-XX Motion passed (or failed)					
A&R	N	ot approved					
Adit	Reas	on:					

	F		renced ction	2.1
0	From			Mahiro Supika (Tokyo Electron)
Comment		Con	nment	Divide the paragraph into 2 paragraphs, one for "silicon wafers with diameters of 300mm and 450mm that comply with SEMI M1" and another for "wafers of other materials with diameters of 300mm and larger."
	Discussion			The concept may be extendable for wafers of other materials with diameter larger than 300mm but no specific coordinate for location of Data Matrix Code is given in the Document
	Х	The	e commit	tee agreed to do one of the following actions.
	^	*No	motion	is required in this step.
			No furth	er action was taken by the committee.
Σ			Refer to	the task force for more consideration.
Action		Х	New Bus	siness
n p			Other	
proposed	Editorial Change			

		Case '	1: No vote in this section :			
		To be included and voted on in § 5. Summary of Editorial Changes.				
		Case 2	2: Voted in this section :			
		Origin "TO" f	al section number and at least one full sentence are required in "FROM" and fields.			
		FROM	1: Section xxx			
1	1	To: Section xxx				
		Justification (If necessary)				
		FROM: Section xxx				
	2	To: Section xxx				
		Justif	ication (If necessary)			
Motio	n by	/2nd	Name (Company)/Name (Company)			
\	/ote		XX-XX Motion passed (or failed)			
A&R		No	ot approved			
ACIN		Reason:				

	F	Referenced Section		5.3.1.1				
C		Fre	om	Mahiro Supika (Tokyo Electron)				
Comment	Comment			Reword "so that the reference point is located the distance as given in Table 1 from the center of the wafer, along a radius $5.0 \pm 0.1^\circ$ counterclockwise from the orientation fiducial axis" to "so that the reference point is located at the radial distance as given in Table 1 from the center of the wafer and at $5.0 \pm 0.1^\circ$ counterclockwise from the primary orientation fiducial axis				
	Discussion			Editorial Change in "V. Summary of Editorial Changes"				
		The	commit	tee agreed to do one of the following actions.				
5	*No n		motion i	is required in this step.				
Action			No furth	er action was taken by the committee.				
Bon			Refer to	the task force for more consideration.				
1			New Bus	siness				
			Other					

	Editorial Change								
li			Case	1: No vote in this section :					
			To be	included and voted on in § 5. Summary of Editorial Changes.					
			Case 2: Voted in this section :						
			Original section number and at least one full sentence are required in "FROM" and "TO" fields.						
			FROM: Section xxx						
		1	To: Section xxx						
			Justification (If necessary)						
			FROM: Section xxx						
		2	To: Section xxx						
			Justification (If necessary)						
N	loti	otion by/2nd Name (Company)/Name (Company)							
		Vot	е	XX-XX Motion passed (or failed)					
	۱&۵	R	No	ot approved					
	101	1	Reason:						

Cor	Referenced Section			3.1					
Comment		Fr	om	Tetsuya Nakai (SUMCO)					
ent		Com	ment	We need to add SEMI M20 in 3.1 SEMI Standards, as a referenced standard.					
Ш	[Discı	Ssion Currently, M20 is not used in T7						
	X	The	e commi	ttee agreed to do one of the following actions.					
	^	*No	motion	is required in this step.					
		Χ		her action was taken by the committee.					
				the task force for more consideration.					
			New Bu	siness					
			Other						
	Editorial Change								
Ac			Case 1:	No vote in this section :					
Action proposed			To be in	ncluded and voted on in <u>§ 5. Summary of Editorial Changes</u> .					
rop			Case 2:	Voted in this section :					
osed			Original section number and at least one full sentence are required in "FRG "TO" fields.						
			FROM: Section xxx						
		1	To: Se	ction xxx					
			Justific	cation (If necessary)					
			FROM:	Section xxx					
		2	To: Section xxx						
			Justification (If necessary)						
N	/loti	ion b	y/2nd	Name (Company)/Name (Company)					
		Vot	е	XX-XX Motion passed (or failed)					
	۱۵Δ	R	Not	approved					
	A&R		Reason	1:					

Defendance d										
CC	Referenced Section			¶5.3.1.1 and Table 1						
mr		Fr	om	John Vally / SunEdison Semiconductor Limited						
Comment	Comment			Please withdraw my negative on Ballot #5752. I agree that my proposed changes can be discussed as New Business.						
		Discu	ussion							
	Х	The	e commit	ttee agreed to do one of the following actions.						
	^	*No	motion	is required in this step.						
			No furth	er action was taken by the committee.						
			Refer to	the task force for more consideration.						
		Х	New Bu	usiness						
			Other							
	Editorial Change									
Act			Case 1:	No vote in this section :						
Action proposed			To be in	ncluded and voted on in <u>§ 5. Summary of Editorial Changes</u> .						
orop			Case 2:	Voted in this section :						
osed			Origina "TO" fie	I section number and at least one full sentence are required in "FROM" and elds.						
			FROM:	Section xxx						
		1	To: Se	ction xxx						
			Justific	Justification (If necessary)						
			FROM: Section xxx							
		2	To: Section xxx							
			cation (If necessary)							
N	/lot	ion b	y/2nd	Name (Company)/Name (Company)						
		Vot	e	XX-XX Motion passed (or failed)						
	A&R			approved						
			Reason							

V. Summary of Editorial Changes

Note: Original section number and at least one full sentence are required in "FROM" and "TO" fields.

FROM: Section 2.1 2.1 This specification defines the geometric and spatial relationships and content (including the error checking and correcting code) of a rectangular two-dimensional (2-D), machine-readable, binary data matrix code symbol for back surface marking of double-side polished silicon wafers with diamters of 300 mm and 450 mm that comply with SEMI M1 and wafers of other materials with diameters of 300 mm and larger. TO: Section 2.1 2.1 This specification defines the geometric and spatial relationships and content (including the error checking and correcting code) of a rectangular two-dimensional (2-D), machine-readable, binary data matrix code symbol for back surface marking of double-side polished silicon wafers with diameters of 300 mm and 450 mm that comply with SEMI M1 and wafers of other materials with diameters of 300 mm and larger. Justification: (If necessary) FROM: Section 5.1 Figure 1 and Figure 2 TO: Section 5.1 Figure 1 and Figure 2 The symbol $\stackrel{\P}{\leftarrow}$ in Figure 1 is changed to $\stackrel{\P}{\leftarrow}$ in using Figure 2. Add a NOTE 'the symbol means "Center Line".' in both Figure 1 and Figure 2. Justification: (If necessary) FROM: Section 5.3.1.1 The 8 row x 32 column rectangular 2-D matrix code symbol shall be placed so that the reference point is located the distance as given in Table 1 from the center of the wafer, along a radius 5.0 ± 0.1° counterclockwise from the orientation fiducial axis. TO: Section 5.3.1.1 The 8 row x 32 column rectangular 2-D matrix code symbol shall be placed so that the reference point is located at the radial distance as given in Table 1 from the center of the wafer and at 5.0 ± 0.1° counterclockwise from the orientation fiducial axis. Justification: (If necessary) Motion To approve the above editorial changes **Motion** Mitsuhiro Matsuda (Hitachi Kokusai Electric) / Tetsuya Nakai (SUMCO) by/2nd by **Discussion** None Vote 7-0 Motion passed Not approved A&R Reason:

VI. Approval Conditions Check

APPROVAL CONDITION 1: All negatives have been discussed and were withdrawn, found not related, or not persuasive. (Regulations ¶ 9.6.2)

APPROVAL CONDITION 2: At least 90% of the sum of the valid accept and reject votes must be accept. (Regulations ¶ 9.6.3)

Note: if both approval conditions are not satisfied, the document fails.

		Accepts		(Accepts + Valid Rejects)			
Approval Rate	=	21	/	21	=	100.0%	>=90%

A&R	Not approved
Ααπ	Reason:

VII. Safety Check See § 14 of the Regulations for further information

V	X	This is not a Safety Document: when all safety-related information is removed, the documer still technically sound and complete.						
Motion:		This is a Safety Document: when all safety-related information is removed, the document is nechnically sound and complete.						
	Safety Checklist (Regulations ¶ 14.3) is complete and has been included with the doc throughout the balloting process.							
N	/loti	otion by/2nd by			Mitsuhiro Matsuda (Hitachi Kokusai Electric) / Tetsuya Nakai (SUMCO)			
	D	Discussion			None			
		Vote			5-0 Motion passed			
	A&F	0		Not a	pproved			
	AXI	Reason:						

VIII. Intellectual Property Check

Note: This ballot may be all or part of a Standard or Safety Guideline. This IP check applies to the entire Standard or Safety Guideline. See § 15 of the Regulations for further information

	to the entire Standard or Safety Guideline. See § 15 of the Regulations for further information								
Х		e meeting chair asked those present in person or by electronic link, if they were aware of any tentially material patented technology or copyrighted items* in the Standard or Guideline.							
	Χ		ootentially n known	GO TO SECTION IX					
		knov	entially mate wn but a Le n material h	GO TO SECTION IX					
			own but an LOA or d or presented to the						
	M		Ask ISC for special permission to publish						
	MOTION		Quit activity						
)N		Wait for L	OA for patented technology or release of copyrighted items.					
	Мо	tion b	y/2 nd by	Name (Company)/Name (Company)					
		Discus	ssion	XXXX					
		Vo	te	XX-XX					
	_	inal A	Action	Motion Passed					
	Г	iiiai <i>F</i>	CUOII		Motion Failed				
	&R Not appro			ved					
A	O(T)	Reason:							

^{*} Note: Such potentially material patented technology or copyrighted items might have become known since the Standard or Safety Guideline was last reviewed, or might become relevant due to this ballot.

IX. Action for this document

		This document passed committee review as balloted and will be forwarded to the A&R for procedural review.									
Motion	X	This document passed committee review with editorial changes and will be forwarded to the A&R for procedural review.									
		Th	This document failed committee review and will be returned to the task force for rework.								
		Th	is do	cun	nent	failed committee review and work will be discontinued.					
ı	Vloti	tion by/2nd by		Mitsuhiro Matsuda (Hitachi Kokusai Electric) / Tetsuya Nakai (SUMCO)							
	Dis	cussion			None						
		Vote		7-0							
	Eina	nal Action			Χ	Motion passed					
	1 1116	iai Action			Motion failed						
		_		Ap	pproved						
	A&F			No	ot ap	proved					
				on:							